

CLAIMS

1. A high-speed production method of a printed circuit board, comprising the steps of:

5       melting and jet-spraying a solid ink on an insulating substrate to be patterned, leaving portions corresponding to an image part unsprayed;

coating a side of the insulating substrate patterned with a conductive layer; and

10       removing solid ink portions by solving.

2. The high-speed production method of a printed circuit board according to claim 1, wherein the solid ink comprises a wax as a main component.

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3. The high-speed production method of a printed circuit board according to claim 1, wherein the melted solid ink is jet-sprayed for patterning in accordance with data from a computer.

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